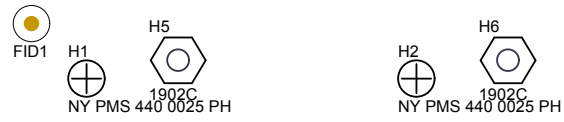


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Number: XX####	Rev: E1	Designed for: Public Release	Mod. Date: 8/7/2013
SVN Rev: Not in version control	Assembly Variant: 001	Project Title: Change in menu Project\Project Options\Parameter	Sheet Title:
Drawn By:	File: PMP7943 rev1.SchDoc	Sheet: 1 of 1	Size: B
Engineer: Enter name of project lead	Contact: http://www.ti.com/support		

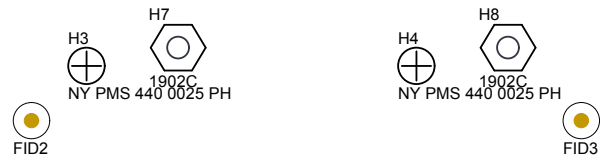


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PCB Number: XX####  
PCB Rev: E1

PCB LOGO  
Texas Instruments



LBL1

PCB Label

Size: 0.65" x 0.20"

ZZ1

Label Assembly Note

This Assembly Note is for PCB labels only

ZZ2

Assembly Note

These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3

Assembly Note

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4

Assembly Note

These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.

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Number: XX####	Rev: E1	Designed for: Public Release	Mod. Date: 5/10/2013
SVN Rev: Not in version control	Assembly Variant: 001	Project Title: Change in menu Project Project Options Parameter	Sheet: 1 of 1
Drawn By:	File: PMP7943 Hardware_ANSI-B_SchDoc	Sheet Title:	Size: B
Engineer: Enter name of project lead	Contact: http://www.ti.com/support		



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Revision History	
Revision	Notes

Place Block Diagram here (if appropriate) or delete this text box.  
 If using a block diagram from another tool, save the picture as a .bmp file.  
 Then, use menu Place|Drawing Tools|Graphic to insert the .bmp file on the schematic.

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Number: <b>XX####</b>	Rev: <b>E1</b>	Designed for: <b>Public Release</b>	Mod. Date: <b>5/10/2013</b>
SVN Rev: <b>Not in version control</b>	Assembly Variant: <b>001</b>	Project Title: <b>Change in menu Project Project Options Parameter</b>	Sheet: <b>1 of 1</b>
Drawn By:	File: <b>PMP7943_Cover Sheet_ANSI-B_SchDoc</b>	Sheet Title:	Size: <b>B</b>
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